

Title (en)
ELECTRONIC CHIP DEVICE WITH IMPROVED THERMAL RESISTANCE AND ASSOCIATED MANUFACTURING PROCESS

Title (de)
ELEKTRONISCHE CHIPVORRICHTUNG MIT VERBESSERTER WÄRMEBESTÄNDIGKEIT UND ZUGEHÖRIGES HERSTELLUNGSVERFAHREN

Title (fr)
DISPOSITIF DE PUCE ÉLECTRONIQUE À RÉSISTANCE THERMIQUE AMÉLIORÉE, ET PROCÉDÉ DE FABRICATION ASSOCIÉ

Publication
EP 3275016 A1 20180131 (FR)

Application
EP 16714793 A 20160322

Priority
• FR 1552457 A 20150324
• EP 2016056204 W 20160322

Abstract (en)
[origin: WO2016150934A1] Electronic chip (31, 51, 72) device (30, 50) with improved thermal resistance, comprising: at least one electrical connection pad (32, 54, 73) with an electrical interconnecting link (33, 55, 74); at least one thermal pad (34, 61, 76) placed on one side of the chip; at least one heat transfer element (36, 59, 70); and at least one thermal link (35, 57, 75) between the thermal pad (34, 61, 76) and the heat transfer element (36, 59, 70).

IPC 8 full level
H01L 23/367 (2006.01); **H01L 23/433** (2006.01); **H01L 25/065** (2006.01)

CPC (source: CN EP US)
H01L 23/367 (2013.01 - CN US); **H01L 23/4334** (2013.01 - CN EP US); **H01L 24/45** (2013.01 - CN); **H01L 24/48** (2013.01 - CN US); **H01L 24/85** (2013.01 - CN US); **H01L 25/0657** (2013.01 - CN EP US); **H01L 23/13** (2013.01 - CN EP US); **H01L 24/45** (2013.01 - EP US); **H01L 2224/45144** (2013.01 - CN EP US); **H01L 2224/48091** (2013.01 - EP US); **H01L 2224/4824** (2013.01 - CN EP US); **H01L 2224/73215** (2013.01 - EP US); **H01L 2224/73265** (2013.01 - EP US); **H01L 2224/85205** (2013.01 - CN US); **H01L 2225/06513** (2013.01 - CN EP US); **H01L 2225/06589** (2013.01 - CN EP US); **H01L 2924/00** (2013.01 - CN)

Citation (search report)
See references of WO 2016150934A1

Designated contracting state (EPC)
AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)
BA ME

DOCDB simple family (publication)
WO 2016150934 A1 20160929; CN 108496248 A 20180904; CN 108496248 B 20211126; EP 3275016 A1 20180131; FR 3034253 A1 20160930; FR 3034253 B1 20180907; JP 2018509771 A 20180405; JP 6789968 B2 20201125; KR 102524167 B1 20230420; KR 20170129889 A 20171127; US 2018061731 A1 20180301

DOCDB simple family (application)
EP 2016056204 W 20160322; CN 201680023557 A 20160322; EP 16714793 A 20160322; FR 1552457 A 20150324; JP 2017549680 A 20160322; KR 20177030185 A 20160322; US 201615560479 A 20160322